JOCT147XH-W8

Rev.A.1.0

DESCRIPTION:

The products are transistor opto-couplers in a plastic WSOP8 package. The device which is infrared LED chip and photo-transistor chip is assembled on lead frame, in order to change the electricity-light-electricity. The products are widely used in transmission and conversion of digital logic, power control and switch, electric insulation and impedance conversion between circuits systems.

MAIN FEATURES

High isolation 7500 VRMS
CTI ≥ 600
Operating temperature range -55°C to 110°C
RoHS & REACH Compliance
HBM: H3A; MM: M4; CDM:C3
CQC approved
VDE approved
UL approved

ABSOLUTE } RA INGS

[redacted]

Ltd.

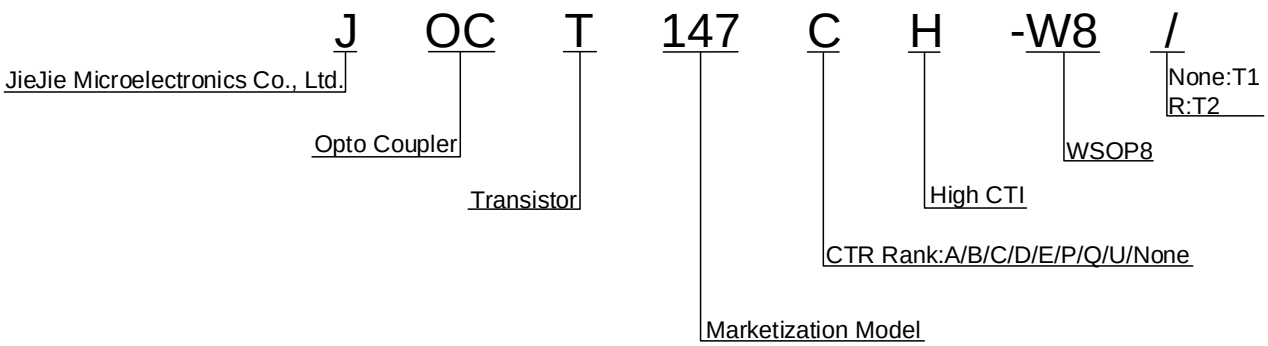
Unit
V
μA
N

CTR

TEL

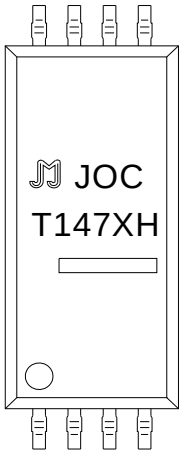
	I_F=0.5mA,V_{CE}=5V		
	I_F=5mA,V_{CE}=5V		

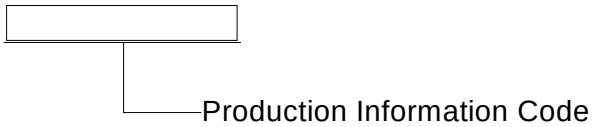
ORDERING INFORMATION



Packing Quantity			
Option	**Quantity**	**Quantity – Inner box**	**Quantity –Outer box**

MARKING





Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

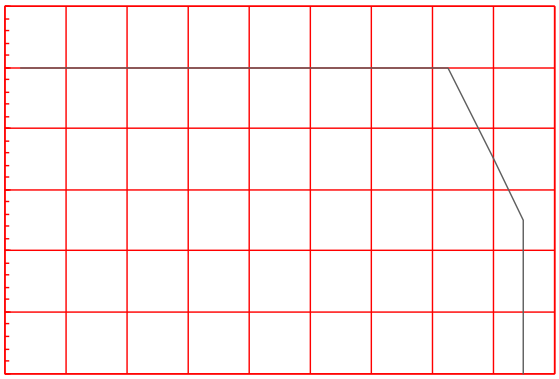


FIG.2: Collector Power Dissiption vs. Ambient Temperature

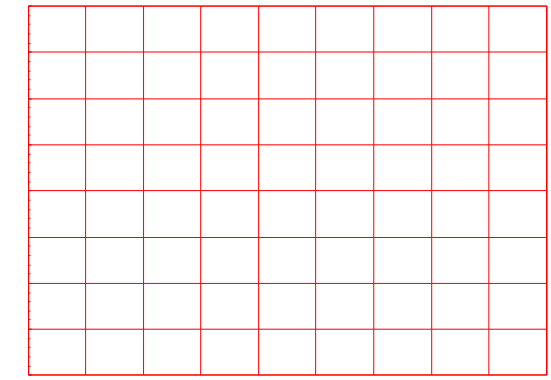


FIG.7: Current Transfer Ratio vs. Forward Current

FIG.8: Current Transfer Ratio vs. Ambient Temperature

Test Circuits

FIG.12: Test Circuits of Turn On Time

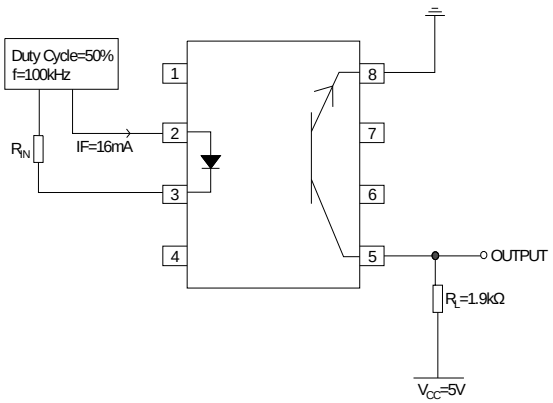
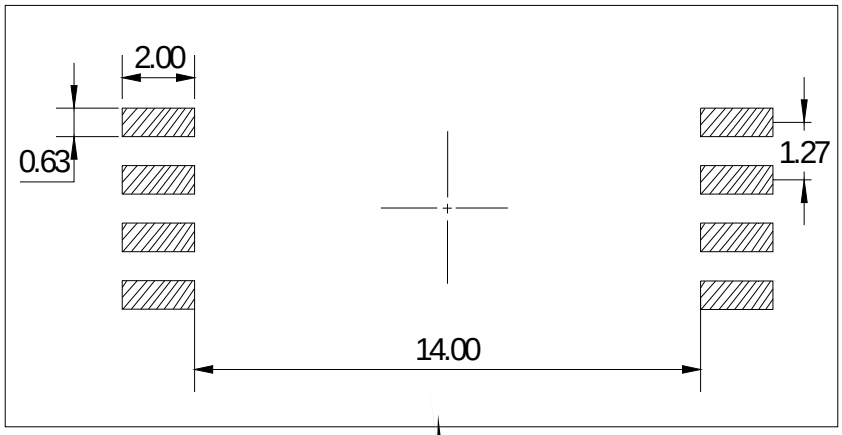


FIG.13: Waveforms of Turn On Time

Package Dimension (Unit: mm)

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A						
B						
C						
D						
E						
F						
G						
H						
I						
J						

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

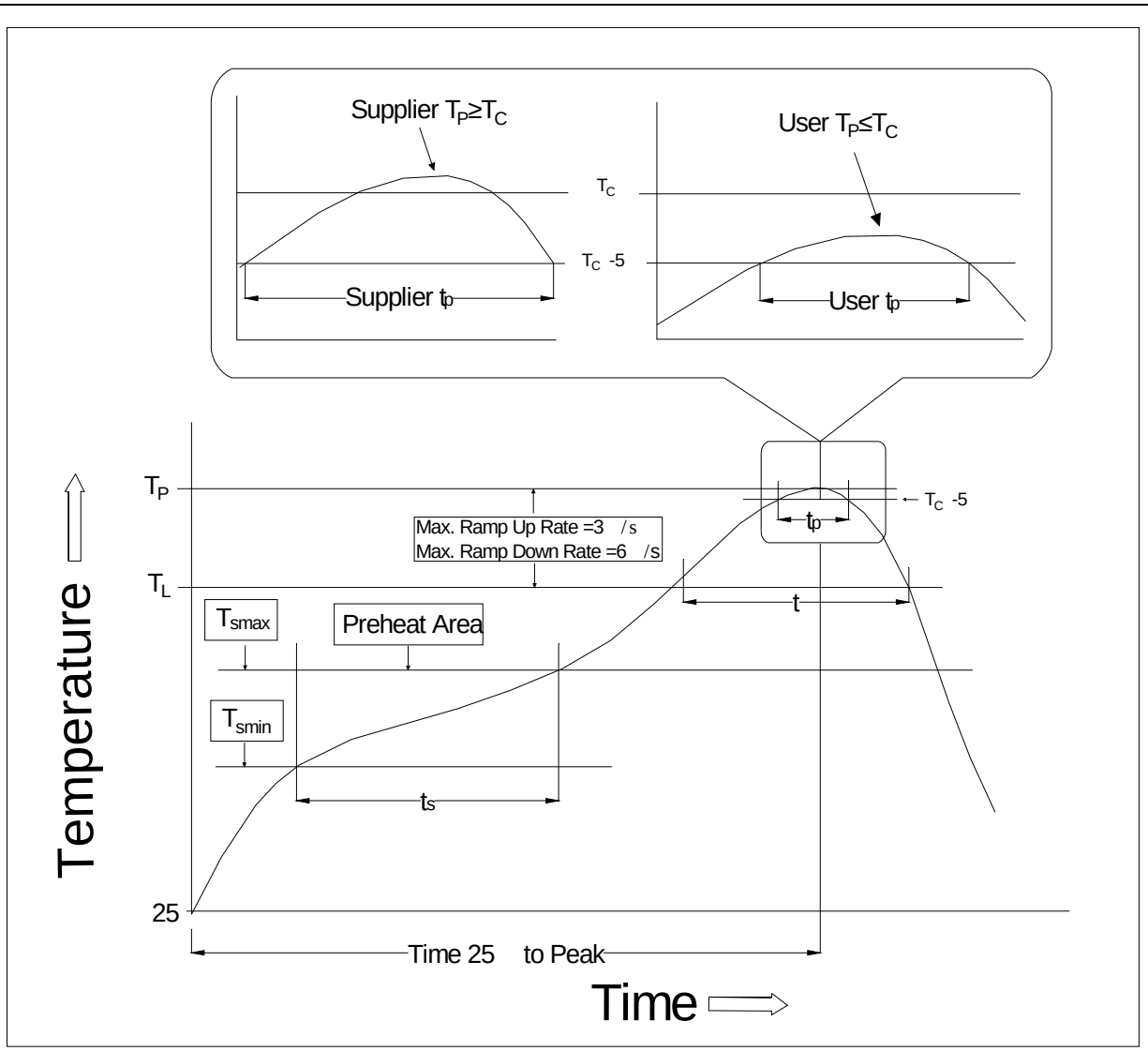


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)





REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 N of 260 T L M0		

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co., Ltd. assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document supersedes and replaces all information previously supplied.

is a registered trademark of Jiangsu JieJie Microelectronics Co., Ltd.

Copyright © 2026 Jiangsu JieJie Microelectronics Co., Ltd. All rights reserved.